

1. (Twice Amended) A device for cooling electronics comprising

(a) a container having a receptacle for receiving an electronic device, the container having an inner wall and an outer wall defining a chamber therebetween that is partially filled with a liquid coolant, wherein the receptacle is disposed between the electronic device and the chamber;

- (b) a wick structure positioned within the container; and
- (c) a surface connected with the container for receiving a cooling conduit.

2. (Twice Amended) The device for cooling electronics of claim 1 wherein the wick structure comprises a first wick structure lining the inside of the outer wall, a second wick structure lining the inside of the inner wall, and a communicating wick structure that periodically connects the first and second wick structures.

6. (Amended) The device for cooling electronics of claim 1 wherein the surface is defined by and integral with the inner wall.

10. (Twice Amended) A method for cooling electronics comprising:

(a) providing a container having a receptacle for receiving an electronic device, the container having an inner wall and an outer wall defining a chamber therebetween; wherein the container is connected to a surface for receiving a cooling conduit;

- (b) filling the container partially with a liquid coolant such that the liquid coolant does not contact both the inner wall and the outer wall simultaneously;
- (c) providing an electronic device;
- (d) connecting the electronic device to the receptacle of the container, wherein the receptacle is disposed between the electronic device and the chamber;